

SOT804-4

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

13 September 2019

Package information

1 Package summary

Terminal position code Q (quad)

Package type descriptive code HVQFN64

Package type industry code HVQFN64

Package style descriptive code HVQFN (thermal enhanced very thin quad

flatpack; no leads)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 27-05-2010

Manufacturer package code 98ASA01102D

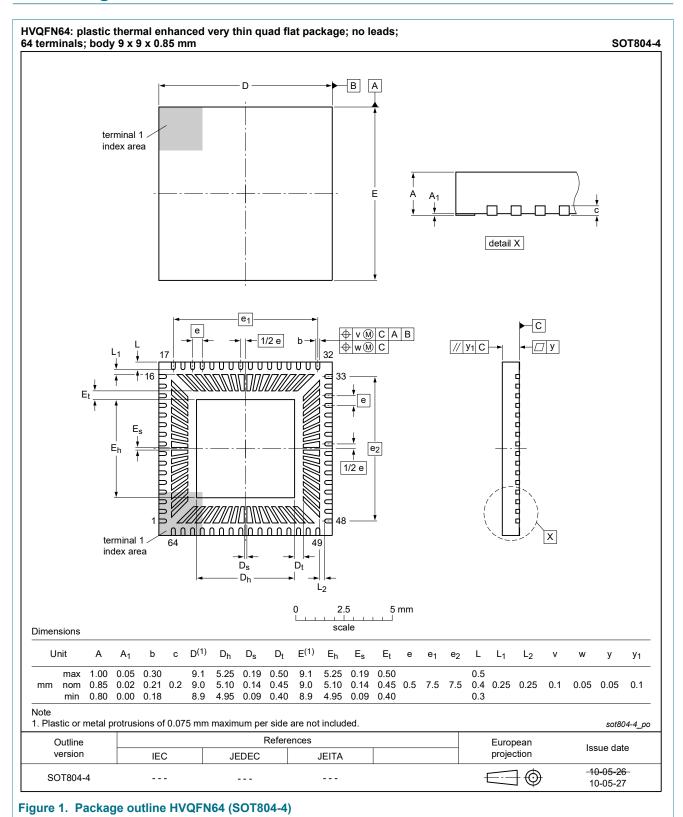
Table 1. Package summary

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Parameter	Min	Nom	Max	Unit		
package length	8.9	9	9.1	mm		
package width	8.9	9	9.1	mm		
seated height	0.8	0.85	1	mm		
nominal pitch	-	0.5	-	mm		
actual quantity of termination	-	64	-			



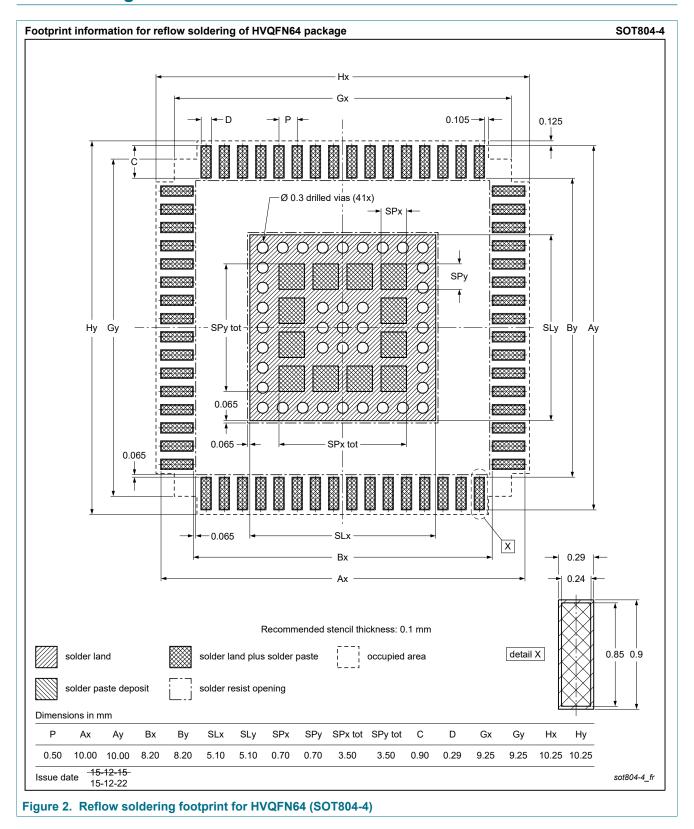
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2 Package outline



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3 Soldering



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4 Legal information

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